METHOD FOR FILLING METAL AND SUBSTRATE PROCESSING DEVICE

ABSTRACT

A method of embedding a metal in a recess formed in a substrate, includes: forming a metal nitride film on the substrate having the recess and embedding a metal nitride in the recess; and subsequently, forming a metal film of a metal contained in the metal nitride on an upper surface of the metal nitride film to cause nitrogen atoms to diffuse from the metal nitride film toward the metal film, and keeping the recess filled with the metal having a reduced nitrogen content.

(Fig. 2E)